

28. (Twice Amended) A method for making a substrate to package a die, the method comprising:

forming a first portion of the substrate using ceramic materials, the first portion comprising an upper surface and a lower surface and including at least one capacitor between the upper and lower surfaces, the at least one capacitor having first and second terminals;

forming a second portion of the substrate using organic materials, the second portion comprising a plurality of conductors therein, including a first conductor coupled to the first terminal and a second conductor coupled to the second terminal, the second portion overlying the first portion; and

forming a first plurality of lands on a surface of the second portion of the substrate, including a first land coupled to the first conductor, and a second land coupled to the second conductor, wherein the first and second lands are positioned to couple to first and second power supply nodes of the die.

30. (Amended) The method recited in claim 28 and further comprising:

forming a second plurality of lands on the lower [a] surface of the first portion of the substrate, including a third land coupled to the first terminal, and a fourth land coupled to the second terminal, and wherein forming the second portion comprises fanning out the plurality of conductors from a first pitch of the first plurality of lands to a second pitch of the second plurality of lands.

Please add new claims 31-40 as follows:

31. A multilayer substrate to mount a die comprising:

a ceramic portion comprising an upper surface and a lower surface and including a capacitor located between the upper and lower surfaces, the capacitor having first and second terminals; and

an organic portion comprising an upper surface having a first plurality of lands thereon, including a first land coupled to the first terminal and a second land coupled to the second

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terminal, wherein the first and second lands are positioned to couple to corresponding power supply nodes of the die, the organic portion further including a plurality of conductors, including a first conductor coupling the first land to the first terminal and a second conductor coupling the second land to the second terminal.

32. The multilayer substrate recited in claim 31 and further comprising a second plurality of lands on the lower surface of the ceramic portion, including a third land coupled to the first terminal and a fourth land coupled to the second terminal.

33. The multilayer substrate recited in claim 32, wherein the pitch of the second plurality of lands is greater than the pitch of the first plurality of lands, and wherein the pitch is increased within the organic portion.

34. The multilayer substrate recited in claim 32, wherein the first plurality of lands further comprises a fifth land positioned to couple to a corresponding signal node of the die, and wherein the second plurality of lands comprises a sixth land coupled to the fifth land via a conductive path that comprises one of the plurality of conductors.

35. The multilayer substrate recited in claim 34, wherein the pitch of the second plurality of lands is greater than the pitch of the first plurality of lands, and wherein the pitch is increased within the organic portion.

36. The multilayer substrate recited in claim 32, wherein the third and fourth lands are positioned to couple to corresponding power supply nodes of an additional substrate underlying the ceramic portion.

37. The multilayer substrate recited in claim 31, wherein the capacitor comprises at least one high permittivity layer.

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